

L Number	Hits	Search Text	DB	Time stamp
1	415	257/706 and (laser or "LED" or light near emit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:15
2	481	257/433 and (laser or "LED" or light near emit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:20
3	301	257/707 and (laser or "LED" or light near emit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:24
4	253	(257/712 or 257/713 or 257/714) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:31
5	101	(257/715 or 257/716 or 257/717) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:31
6	139	(257/718 or 257/719 or 257/720 or 257/721) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:34
7	920	(385/88 or 438/122 or 372/36) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:47
8	1052	(semiconductor or die or chip or IC) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43) with (double or dual or both or multi\$4 or second)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:49
9	839	((semiconductor or die or chip or IC) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43) with (double or dual or both or multi\$4 or second)) not ((385/88 or 438/122 or 372/36) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:50
10	804	((semiconductor or die or chip or IC) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43) with (double or dual or both or multi\$4 or second)) not (((385/88 or 438/122 or 372/36) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)) or (257/706 and (laser or "LED" or light near emit\$3)) or (257/433 and (laser or "LED" or light near emit\$3)) or (257/707 and (laser or "LED" or light near emit\$3)) or ((257/712 or 257/713 or 257/714) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:50
-	1	5454002.pn./	USPAT	2004/04/28 03:48

-	1	5454002.pn. and isolat\$3 with attach\$3	USPAT	2004/04/28 04:12
-	1	(light near emitting near device) and adhesive with solder with heat near sink	USPAT	2004/04/28 04:38
-	0	(light near emitting near device) and adhesive with solder with heat near sink with second near heat	USPAT	2004/04/28 04:38
-	0	(light near emitting near device) and adhesive with heat near sink with second near heat	USPAT	2004/04/28 04:38
-	0	(light near emitting near device or laser or LED) and adhesive with solder with heat near sink with second near heat	USPAT	2004/04/28 04:39
-	6	(light near emitting near device or laser or LED) and adhesive with heat near sink with second near heat	USPAT	2004/04/28 04:43
-	0	(light near emitting near device or laser or LED) and adhesive with heat near sink with heat near stiffener	USPAT	2004/04/28 04:44
-	6	(light near emitting near device or laser or LED) and adhesive with heat near sink with stiffener	USPAT	2004/04/28 04:46
-	337	(light near emitting near device or laser or LED) and adhesive with heat near sink with heat	USPAT	2004/04/28 04:49
-	81	((light near emitting near device or laser or LED) and adhesive with heat near sink with heat) and adhesive with heat near sink with heat and adhesive with solder	USPAT	2004/04/28 04:52
-	3	((light near emitting near device or laser or LED) and adhesive with heat near sink with heat) and adhesive with heat near sink with heat and adhesive with solder and ("AuGe" or "PbSn")	USPAT	2004/04/28 04:52